

SOT1625-2

plastic, ball grid array; 783 bumps; 1.0 mm pitch; 29 mm x 29 mm x 3.13 mm body

16 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA783
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	11-01-2016
Manufacturer package code	98ASA00295D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	29	-	mm
package width	-	29	-	mm
seated height	2.966	3.13	3.294	mm
package height	1.05	1.17	1.29	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	783	-	



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2 Package outline

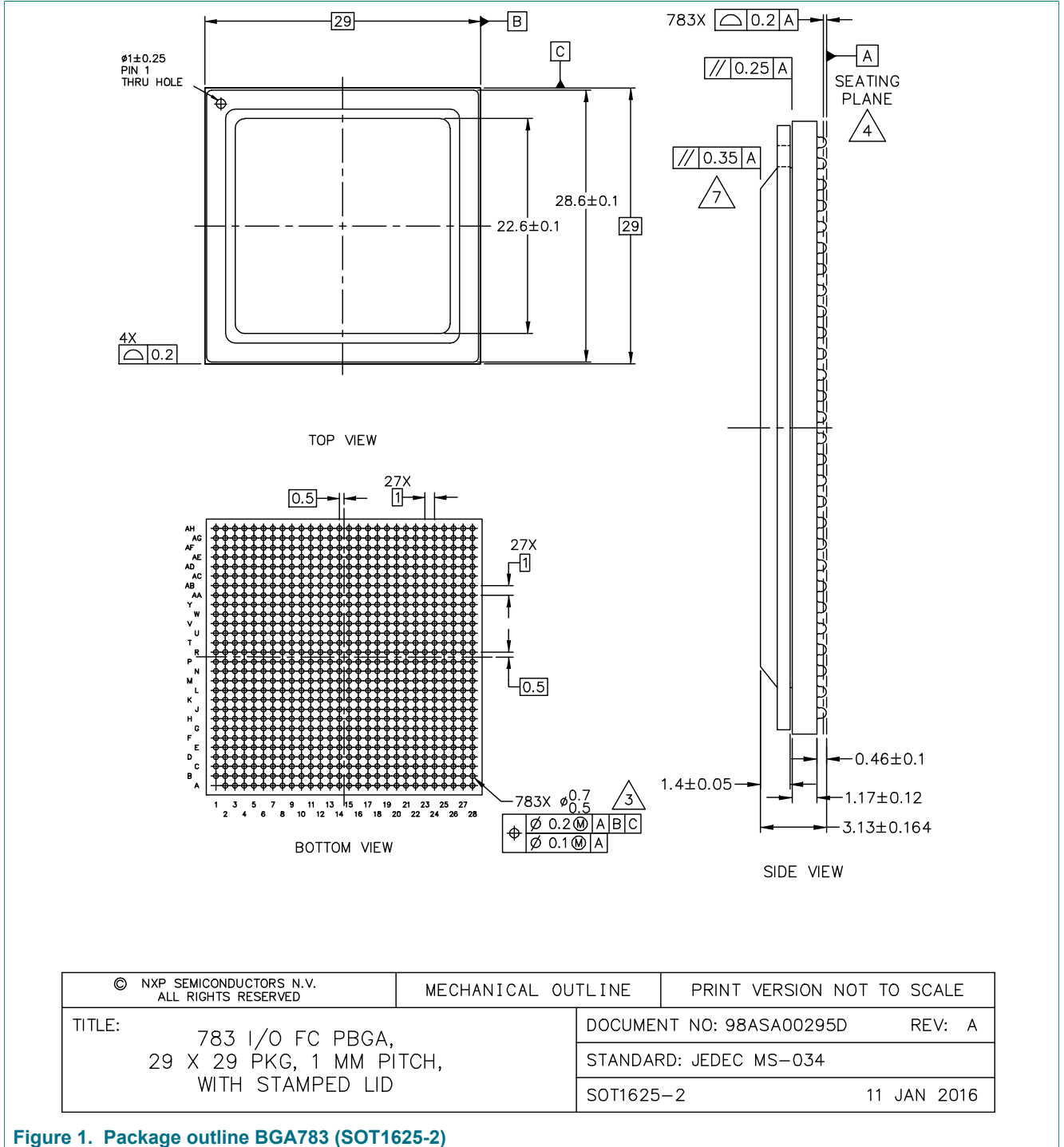


Figure 1. Package outline BGA783 (SOT1625-2)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.
7. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
8. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: 783 I/O FC PBGA, 29 X 29 PKG, 1 MM PITCH, WITH STAMPED LID	DOCUMENT NO: 98ASA00295D	REV: A
	STANDARD: JEDEC MS–034	
	SOT1625–2	11 JAN 2016

Figure 2. Package outline note BGA783 (SOT1625-2)

3 Legal information

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